

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-307608

(43)Date of publication of application : 23.10.2002

(51)Int.Cl. B32B 15/08
B32B 7/12
B32B 27/34
B32B 27/38
H05K 3/00
H05K 3/38
H05K 3/46

(21)Application number : 2001-112049

(71)Applicant : KANEGAFUCHI CHEM IND CO LTD

(22)Date of filing : 10.04.2001

(72)Inventor : SHIMOOOSAKO KANJI

ITO TAKU

NISHINAKA MASARU

(54) LAMINATE MANUFACTURING METHOD AND MULTILAYERED PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for efficiently manufacturing a laminate suitable for a build-up method under such a condition that an adhesive layer has sufficient adhesiveness, and a multilayered printed wiring board using the laminate.

SOLUTION: The laminate is manufactured by laminating a metal foil 1 to one surface of a polymeric film 10 through a first adhesive layer 11 and laminating a second thermosetting adhesive layer 12 to the other surface of the polymeric film 10. Alternatively, an adhesive is applied to both surfaces of the polymeric film 10 to be dried to bring the adhesive layers on both surfaces of the polymeric film 10 to a semicured state and the metal foil 13 is laminated to the adhesive layer 11 on the single surface under a condition capable of holding the adhesive layers on both surfaces to the semicured state.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision
of rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

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